TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (π-MOSVI)

TPC8102

Lithium Ion Battery Applications Notebook PCs Portable Equipment Applications

• Small footprint due to small and thin package

• Low drain-source ON resistance : $RDS(ON) = 34 \text{ m}\Omega \text{ (typ.)}$

• High forward transfer admittance : $|Y_{fs}| = 9 S \text{ (typ.)}$

• Low leakage current : $I_{DSS} = -10 \mu A \text{ (max) (V}_{DS} = -30 \text{ V)}$

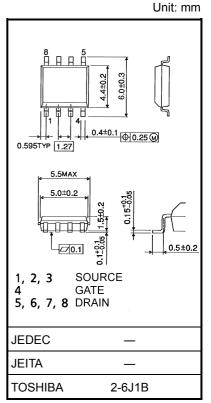
• Enhancement-mode : $V_{th} = -0.8 \sim -2.0 \text{ V (V}_{DS} = -10 \text{ V}, \text{ ID} = -1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characte	ristics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	-30	V	
Drain-gate voltage (R	$k_{GS} = 20 \text{ k}\Omega$	V_{DGR}	-30	V	
Gate-source voltage		V_{GSS}	±20	V	
Drain current	DC (Note 1)	ΙD	-6	Α	
Drain current	Pulse (Note 1)	I_{DP}	-24	A	
Drain power dissipati	on (t = 10 s) (Note 2a)	P_{D}	2.4	W	
Drain power dissipati	on (t = 10 s) (Note 2b)	P_{D}	1.0	W	
Single pulse avalanch	ne energy (Note 3)	E _{AS}	47	mJ	
Avalanche current		I _{AR}	-6	Α	
Repetitive avalanche	energy Note 2a) (Note 4)	E _{AR}	0.24	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature	range	T _{stg}	−55 to 150	°C	

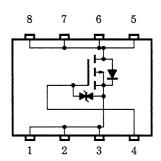
Note: For (Note 1), (Note 2), (Note 3) and (Note 4), please refer to the next page.

This transistor is an electrostatic sensitive device. Please handle with caution.



Weight: 0.080 g (typ.)

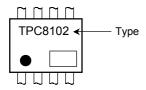
Circuit Configuration



Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R _{th (ch-a)}	52.1	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R _{th (ch-a)}	125	°C/W

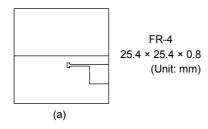
Marking (Note 5)

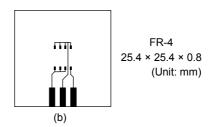


Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a)

(b) Device mounted on a glass-epoxy board (b)





Note 3: V_{DD} = -24 V, T_{ch} = 25°C (initial), L = 1.0 mH, R_G = 25 Ω , I_{AR} = -6 A

Note 4: Reptitve rating; pulse width limited by maximum channel temperature.

Note 5: on lower left of the marking indicates Pin 1.

shows Lot number. (year of manufacture: last decimal digit of the year of manufacture, month of manufacture: january to december are denoted by letters A to L respectively)

2



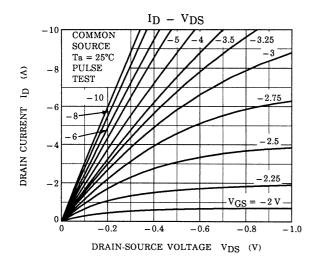
Electrical Characteristics (Ta = 25°C)

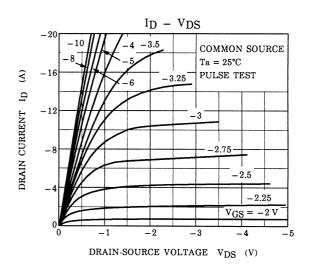
Chara	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage c	urrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cut-off cu	ırrent	I _{DSS}	V _{DS} = -30 V, V _{GS} = 0 V	_	_	-10	μΑ
Drain -source by voltage	oreakdown	V _{(BR) DSS}	I _D = -10 mA, V _{GS} = 0 V	-30	_	-	٧
Gate threshold	voltage	V _{th}	V _{DS} = -10 V, I _D = -1 mA	-0.8	_	-2.0	V
Drain-cource C	M resistance	R _{DS} (ON)	$V_{GS} = -4 \text{ V}, I_D = -3 \text{ A}$	_	56	70	mΩ
Drain-source ON resistance		R _{DS} (ON)	$V_{GS} = -10 \text{ V}, I_D = -3 \text{ A}$	_	34	40	mΩ
Forward transfe	r admittance	Y _{fs}	$V_{DS} = -10 \text{ V}, I_D = -3 \text{ A}$	4.5	9	_	S
Input capacitance		C _{iss}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz	_	1380	_	pF
Reverse transfer capacitance		C _{rss}		_	220	_	
Output capacitance		C _{oss}		_	560	_	
Switching time	Rise time	t _r	$V_{\text{GS}_10 \text{ V}} = -3 \text{ A}$ $V_{\text{OUT}} = -3 A$	_	12	_	
	Turn-on time	t _{on}			20		ns
	Fall time	t _f		1	22	l	. 115
	Turn-off time	t _{off}			90		
Total gate charge (Gate-source plus gate-drain)		Qg		_	43	_	
Gate-source charge		Q _{gs}	$V_{DD} \approx -24 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -6 \text{ A}$	_	30	_	nC
Gate-drain ("miller") charge		Q _{gd}		_	13	_	

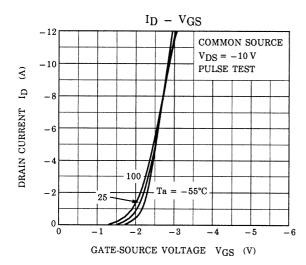
Source-Drain Ratings and Characteristics (Ta = 25°C)

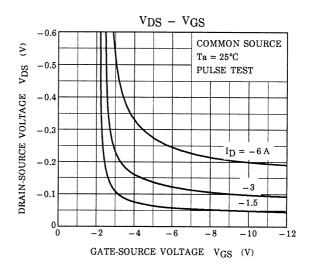
Charact	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	_	_	_	-24	Α
Forward voltage	(diode)	V _{DSF}	$I_{DR} = -6 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	1.2	V

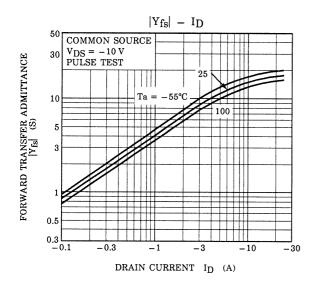
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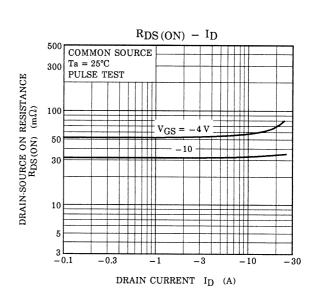


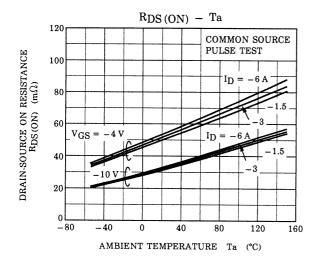


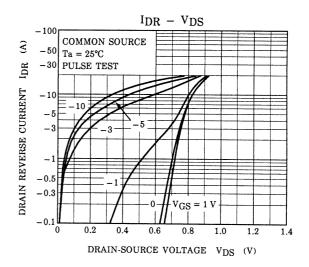


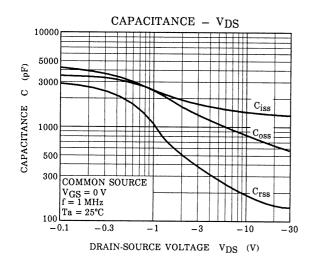


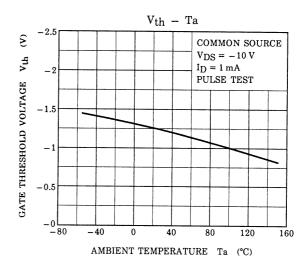


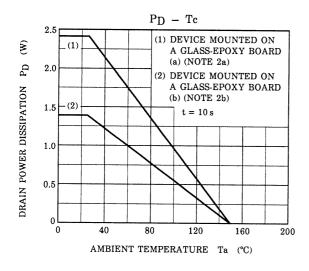


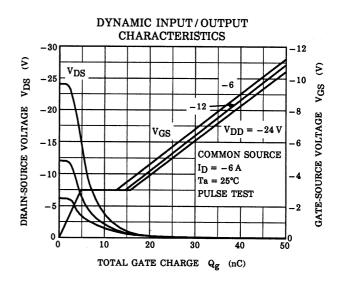




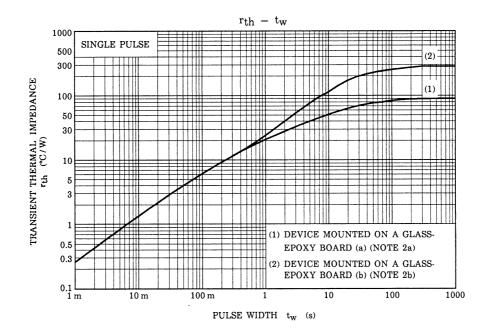


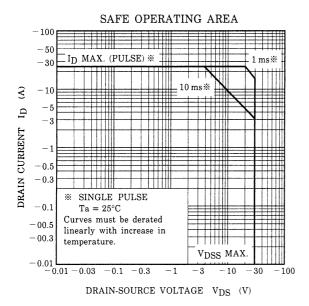


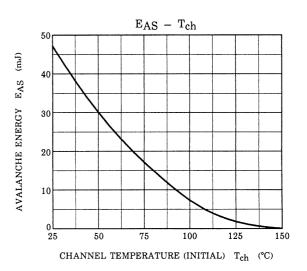


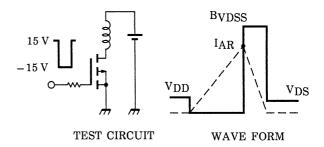


5









$$\begin{array}{l} T_{ch}=25^{\circ}C~(Initial) \\ Peak~I_{AR}=-6~A,~R_{C}=25~\Omega \\ V_{DD}=-24~V,~L=1.0~mH \end{array} \\ \begin{array}{l} E_{AS}=\frac{1}{2}\cdot L\cdot I^{2}\cdot~(\frac{BVDSS}{BVDSS}-V_{DD}) \end{array} \label{eq:charge_energy}$$

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